



# BGA Switch-A-Pitch Adapters

## FEATURES

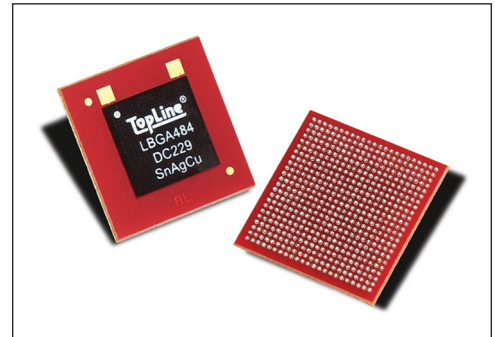
- Reduce HDI construction by adapting smaller pitch devices to larger footprints
- Convert 0.4mm and 0.5mm pitch footprints to 1mm or 1.27mm pitch (Please contact factory for other pitch requirements)
- Enable the use of standard line and trace spacing
- Eliminate the need for laser-drilled microvias motherboards

## GENERAL SPECIFICATIONS

- BOARD MATERIAL: 0.062 thick FR-4 or Rogers 370 HR, with 1/2-oz. Cu traces, both sides
- PADS: finished with ENIG (Electroless Ni Immersion Au), NSMD
- SOLDER SPHERES: 63/37 Sn/Pb or Pb-free SAC 305
- TRACE WIDTH/SPACE: 0.003 [0.762]
- OPERATING TEMPERATURE: 221°F [105°C] FR-4, 266°F [130°C] Pb-free

## MOUNTING CONSIDERATIONS

- SUGGESTED PCB PAD SIZE: 0.022 [0.55] for 1.27mm pitch; 0.020 [0.50] for 1.00mm pitch

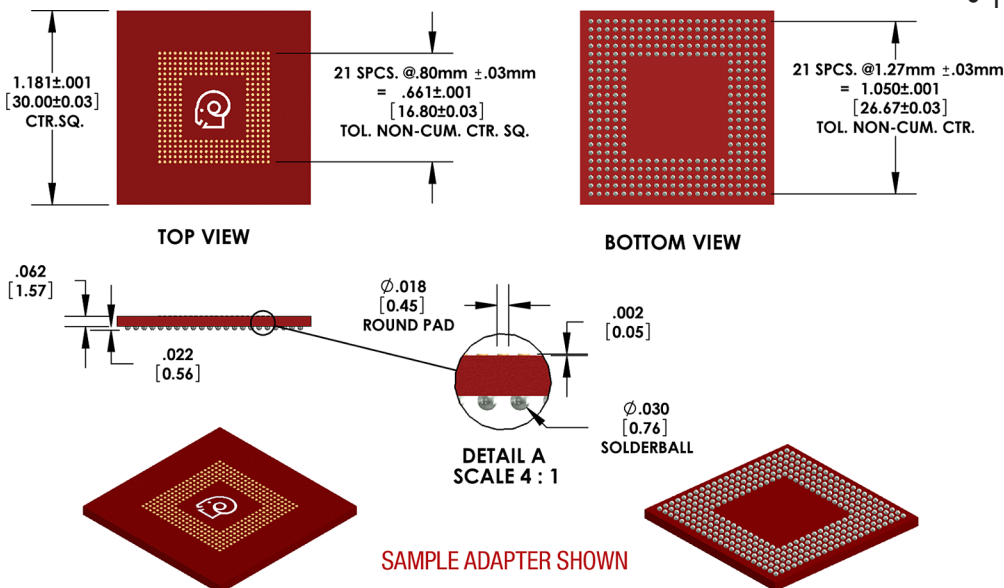


**CUSTOMIZATION:** In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

## ORDERING INFORMATION

To obtain a quote for a specific adapter, please email a request to [info@arieselec.com](mailto:info@arieselec.com) with the following information:

- Your name, company name, and telephone number
- A drawing or data sheet of the device to be placed on adapter (top image)
- A drawing or data sheet of the target footprint for the adapter (bottom image)
- A list of any other design parameters or restrictions that must be considered
- The quantity of adapters to be quoted



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